

ABSTRACT**A STRESS-FREE LEAD FRAME**

The present invention relates to a stress-free lead frame (1) for a semiconductor. The stress-free lead frame (1) is provided with a stress-relief means (15) and an interlocking means (16) at the outer periphery. The stress-relief means (15) is capable of accommodating expansion and compression while the interlocking means (16) take care of shock and vibration during handling to thereby eliminate delamination of the lead frame (10).

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